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Robert
and

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2835
Examiner: M. Datskovskiy

In Re PATENT APPLICATION Of:

Applicant: Seiji ANDOH

Serial No.: 09/376,063

Filed: August 17, 1999

For: PACKAGE STRUCTURE FOR A
SEMICONDUCTOR DEVICE

Attorney Ref: OKI 226

AMENDMENT

August 26, 2002

Commissioner for Patents
Washington, D.C. 20231
Box – Non-Final Office Action

Sir:

This Amendment is filed in response to the Office Action dated May 24, 2002, the time for response to which is up to and including August 26, 2002. Please amend the above-referenced application as follows:

IN THE CLAIMS:

Please cancel claim 30 and amend claims 20, 26 and 28 to read as follows:

20. (Twice Amended) A semiconductor device, comprising:
a substrate having a main surface and a back surface,

wherein said back surface has a central area, an intermediate area in which no bumps are disposed, surrounding the central area, and a peripheral area surrounding said intermediate area:

- a semiconductor chip disposed on said main surface;
a first bump unit disposed in said central area of said back surface.

FEE ENCLOSED:\$
Please charge any further
fee to our Deposit Account
No. 18-0002

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